

ActiLED ActiLED-F3865 Series Active Heat Sinks Φ 38mm for COB Modular Product Brief

Features VS Benefits

- * Mechanical compatibility with direct mounting of the LED modules to the LED cooler and thermal performance matching the lumen packages.
- * Thermal resistance range Rth(1.38°C/W).
- * Modular design with mounting holes foreseen for direct mounting of a wide range of LED modules and COB's:
- * Diameter 38mm - Standard height 65.0mm , Other heights on request.
- * Extruded from highly conductive aluminum.
- 2 standard colors - clear anodised - black anodised
- Zhaga Book 3 Spot Light Modules Edison ,Xicato ,Bridgelux , Osram ,Citizen ,Lumileds ,Cree , Tridonic , Vossloh-Schwabe ,Seoul ,LG ,Lustrous ,Prolight ,Samung , SHARP , Luminus .Philips



- 1) Xicato XSM, XIM,XTM;
- 2) Bridgelux ESS, ESR, Vero 10, Vero 13,Vero 18 V-series;
- 3) Citizen CLL024-CLU028, CLL034-CLU038;
- 4) Cree XLamp CXA13xx, CXA15xx,CSA18xx;
- 5) Lumileds Luxeon COB's 1203, 1204, 1205, Luxeon K arrays K12, K16;
- 6) Osram PrevaLED Core,SOLERIQ P and SOLERIQ S LED engines.
- 7) Seoul Semiconductor ZC6, ZC12, ZC18,ZC25;
- 8) Tridonic TALEXXmodule SLE modules;
- 9) LG Innotek LEMWM18 10W, 13W, 17W
- 10) Edison EdiLex SLM and EdiLex II COB LED engines.
- 11) Lustrous LUSTRON 6 series LL604F, LL608D, LL613F, LL620F
- 12) Prolight Opto PABS, PABA, PACB, PANA
- 13) Samung LC013,LC019,LC026 COB LED engines.
- 14) SHARP Mini Zenigata Intermo and Mega Zenigata LED engines.
- 15) Philips Fortimo SLM LED engines.
- 16) Vossloh-Schwabe LUGA Shop LED engines.
- 17) Luminus C##9,C##14 LED engines.

Order Information

Example:FanLED-F3865-B-#

Example:FanLED-F38 **1** - **2** - **3**

1 Hight (mm)

2 Anodising Color

B-Black

C-Clear

Z-Custom

3 Mounting Options - see graphics for details Combinations available

Ex.order code - 12

means option 1 and 2 combined

MingFa recommends the use of a high thermal conductive interface between the LED module and the LED cooler. Either thermal grease, a thermal pad or a phase change thermal pad thickness 0.1-0.15mm is recommended.

Notes:

- Mentioned models are an extraction of full product range.
- For specific mechanical adaptations please contact MingfaTech.
- MingfaTech reserves the right to change products or specifications without prior notice.

ActiLED ActiLED-F3865 Series Active Heat Sinks Φ 85mm for COB Modular Product Brief

The product data table



Brand	Mingfa Tech		
Series Name	ActiLED Active heat sink		
Series Number	ActiLED-F3865		
Manufacturing Technology	Aluminum extrusion		
Material	AL6063-T5		
Color & Finishing	Black Anodized		
Certification	CE, ROHS, WEEE		
Fan date	Size:25x25x12mm;	Electric power:0.48W;	Speed:2900RPM ;
Diameter(mm)	Φ 38		
Heat sink Height(mm)	50.0mm		
Max. Lumen	3000 lm		
Dissipated Power (Ths-amb,50°C)	20.5 W		
Thermal Resistance Rth (°C/W)	1.38°C/W		
Cooling Surface Area (mm²)	28449.0 mm²		
Net Weight (g)	68.9g		
Quantity(pcs/CTN)	108 pcs		
Modular Types	COB		
For Environments	Indoor area		
For Lightings	Down lights,Architectural lights		
For Application	Retail & Hospitality,Mall & Museums,Office		
For LED brands	Bridgelux,BJB,Citizen,Cree,Edison,GE,LG,Lumileds,Lumens,Luminus,Ledil,Nichia,Osram, Philips,Prolight Opto,Samsung,Seoul,Sharp,Tridonic,Vossloh Schwabe,Xicato,Zhaga		

* 3D files are available in ParaSolid, STP and IGS on request

* The thermal resistance Rth is determined with a calibrated heat source of 14mmx14mm central placed on the heat sink, Tamb 40° and an open environment. Reference data @ heat sink to ambient temperature rise Ths-amb 50°C The thermal resistance of a LED cooler is not a fix value and will vary with the applied dissipated power Pd

* Dissipated power Pd. Reference data @ heat sink to ambient temperature rise Ths-amb 50°C The maximal dissipated power needs to be verified in function of required case temperature Tc or junction temperature Tj and related to the estimated ambient temperature where the light fixture will be placed Please be aware the dissipated power Pd is not the same as the electrical power Pe of a LED module

To calculate the dissipated power please use the following formula: $P_d = P_e \times (1 - \eta_L)$

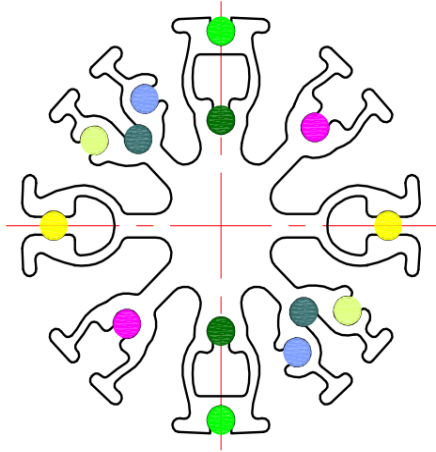
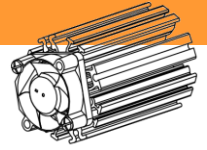
Pd - Dissipated power

Pe - Electrical power

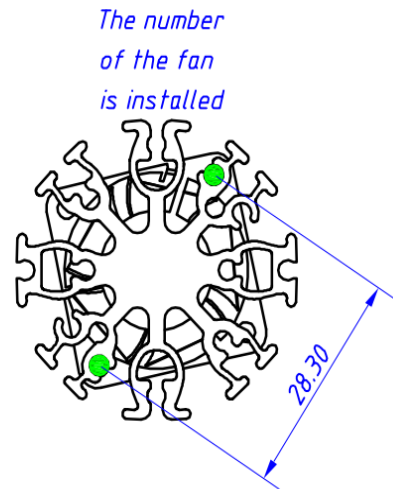
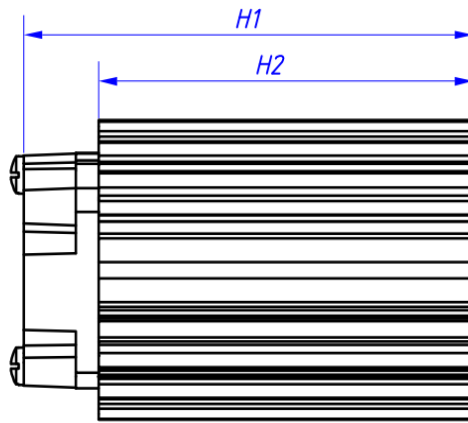
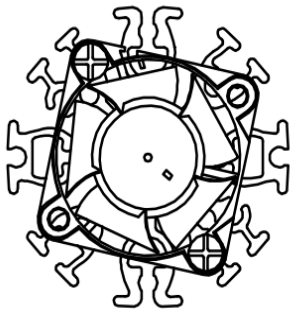
η_L = Light efficiency of the LED module

ActiLED ActiLED-F3865 Series Φ 38mm COB Active Heat Sink Drawings

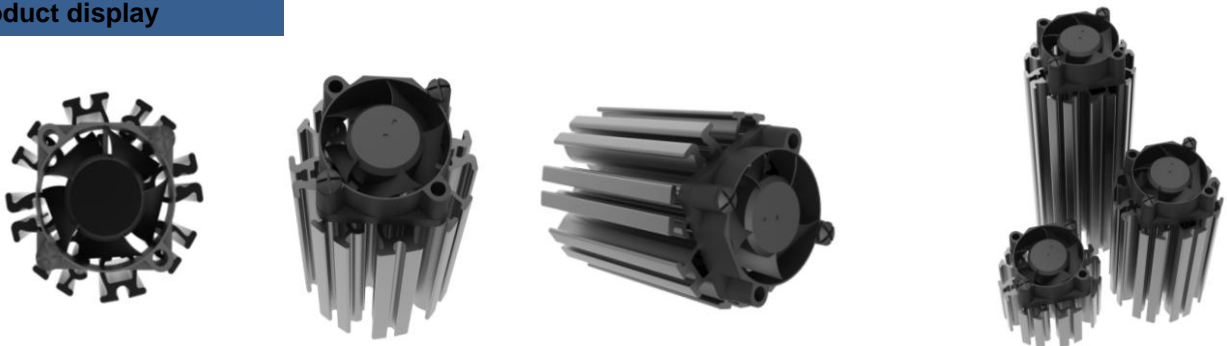
Drawings & Type Selection



No.	Finish	Mounting hole
A1		19.0mm;2xM3@180°
A2		22.0mm;2xM3@180°
A3		25.0mm;2xM3@180°
A4		26.9mm;2xM3@180°
A5		28.3mm;2xM3@180°
A6		31.4mm;2xM3@180°
A7		35.0mm;2xM3@180°



Product display

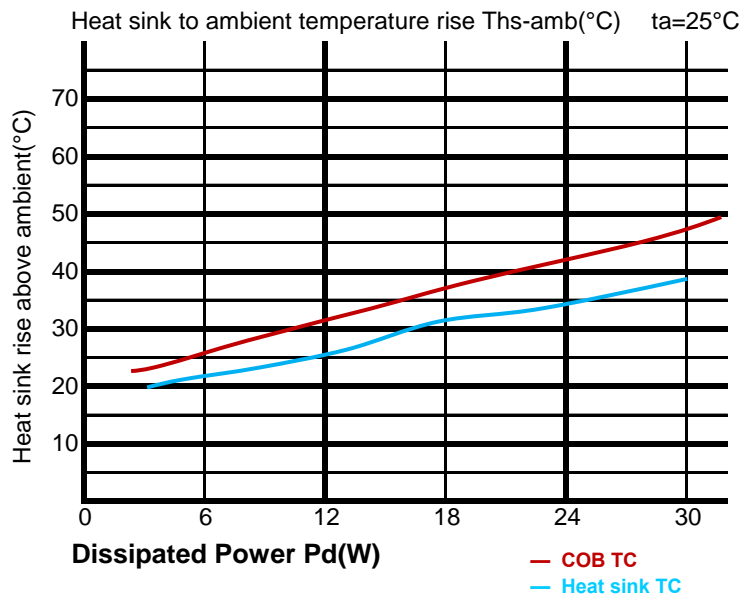


ActiLED ActiLED-F3865 Series Φ 65mm Active Cooling Thermal Data

The thermal data table



Dissipated Power Pd(W)	Pd = Pe x (1-ηL)	
	Heat sink to ambient thermal resistance Rhs-amb (°C/W)	Heat sink to ambient temperature rise Ths-amb (°C)
ActiLED-3865		
4	5.1	21.5
8	2.75	23.7
12	2.02	26.6
16	1.65	29.5
20	1.38	31.7



* Please be aware the dissipated power Pd is not the same as the electrical power Pe of a LED module.

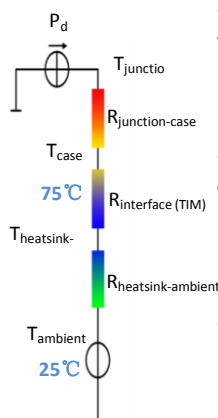
*To calculate the dissipated power please use the following formula: Pd = Pe x (1-ηL).

Pd - Dissipated power ; Pe - Electrical power ; ηL = Light efficiency of the LED module;

*The aluminum substrate side of the package outer shell is thermally connected to the heat sink via TIM (Thermal interface material).

MingFa recommends the use of a high thermal conductive interface between the LED module and the LED cooler.

Either thermal grease, A thermal pad or a phase change thermal pad thickness 0.1-0.15mm is recommended.



*Thermal resistance is a heat property and a measurement of a temperature difference by which an object or material resists a heat flow.

Geometric shapes are different, the thermal resistance is different. Formula: $\theta = (Ths - Ta) / Pd$

θ - Thermal Resistance [°C/W]; Ths - Heatsink temperature ; Ta - Ambient temperature ;

*The thermal resistance between the junction section of the light-emitting diode and the aluminum substrate side of the package outer

shell is $R_{junction-case}$, the thermal resistance of the TIM outside the package is $R_{interface (TIM)}$ [°C/W], the thermal resistance with the heat sink is $R_{heatsink-ambient}$ [°C/W], and the ambient temperature is $T_{ambient}$ [°C].

*Thermal resistances outside the package $R_{interface (TIM)}$ and $R_{heatsink-ambient}$ can be integrated

into the thermal resistance $R_{case-ambient}$ at this point. Thus, the following formula is also used:

$$T_{junction} = (R_{junction-case} + R_{case-ambient}) \cdot Pd + T_{ambient}$$